



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C470JB8NCNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>470</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>C</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| ① Series | Samsung Multi-layer Ceramic Capacitor | | |
|---------------|---------------------------------------|-------------------|-------------------------|
| ② Size | 0603 (inch code) | L: 1.6 ± 0.1 mm | W: 0.8 ± 0.1 mm |
| ③ Dielectric | COG | 8 Inner electrode | Ni |
| Capacitance | 47 pF | Termination | Cu |
| ⑤ Capacitance | ±5 % | Plating | Sn 100% (Pb Free) |
| tolerance | | Product | High-Q |
| Rated Voltage | 50 V | Special | Reserved for future use |
| Thickness | 0.8 ± 0.1 mm | ① Packaging | Cardboard Type, 7" reel |

B. Samsung Reliablility Test and Judgement condition

| | Performance | Test condition | |
|-------------------|--|--------------------------------------|--|
| Capacitance | Within specified tolerance | 1Mb±10% 0.5~5Vrms | |
| Q | 1000 min | | |
| Insulation | 10,000Mohm or 500Mohm⋅ <i>μ</i> F | Rated Voltage 60~120 sec. | |
| Resistance | Whichever is Smaller | | |
| Appearance | No abnormal exterior appearance | Microscope (×10) | |
| Withstanding | No dielectric breakdown or 300% of the rated voltage | | |
| Voltage | mechanical breakdown | | |
| Temperature | COG | | |
| Characterisitcs | (From -55 $^{\circ}$ to 125 $^{\circ}$, Capacitance change shoud be within ±30PPM/ $^{\circ}$) | | |
| Adhesive Strength | No peeling shall be occur on the | 500g·F, for 10±1 sec. | |
| of Termination | terminal electrode | | |
| Bending Strength | Capacitance change : | Bending to the limit (1mm) | |
| | within ±5% or ±0.5pF whichever is larger | with 1.0mm/sec. | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | |
| | | (preheating : 80~120℃ for 10~30sec.) | |
| | | | |
| Resistance to | Capacitance change : | Solder pot : 270±5℃, 10±1sec. | |
| Soldering heat | within ±2.5% or ±0.25pF whichever is larger | | |
| | Tan δ, IR : initial spec. | | |

| | Performance | Test condition |
|------------------|---|-------------------------------------|
| Vibration Test | Capacitance change : | Amplitude : 1.5mm |
| | within ±2.5% or ±0.25pF whichever is larger | From 10Hz to 55Hz (return : 1min.) |
| | Tan δ, IR : initial spec. | 2hours × 3 direction (x, y, z) |
| Moisture | Capacitance change : | With rated voltage |
| Resistance | within ±7.5% or ±0.75pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | Q: 200 min | |
| | IR : 500Mohm or 25Mohm $\cdot \mu$ F | |
| | Whichever is Smaller | |
| High Temperature | Capacitance change : | With 200% of the rated voltage |
| Resistance | within ±3% or ±0.3pF whichever is larger | Max. operating temperature |
| | Q: 350 min | 1000+48/-0hrs |
| | IR : 1000Mohm or 50Mohm $\cdot \mu$ F | |
| | Whichever is Smaller | |
| Temperature | Capacitance change : | 1 cycle condition |
| Cycling | within ±2.5% or ±0.25pF whichever is larger | Min. operating temperature → 25°C |
| | Tan δ, IR : initial spec. | → Max. operating temperature → 25°C |
| | | |
| | | |
| | | 5 cycle test |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.